

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please amend claim 1 and add new claims 6-9 as follows:

LISTING OF CLAIMS:

1. (Currently Amended) An integrated circuit device comprising:
an integrated circuit formed on a first surface of a substrate;
an insulator formed on a second surface opposed to the first surface of the substrate; and
at least one connection pile made of a conductive material filled up in a corresponding unlined hole which is so formed that it the hole penetrates the substrate, the integrated circuit, and the insulator.
2. (Original) The integrated circuit device according to claim 1, wherein a thickness of the insulator is set to not less than 3 nm.
3. (Original) The integrated circuit device according to claim 1, wherein a thickness of the substrate is set to not more than 100 μm .
4. (Original) The integrated circuit device according to claim 1, wherein a circuit as a target in electrical connection formed in the integrated circuit is electrically connected to the connection pile.
5. (Original) An electronic device comprising a plurality of the integrated circuit devices according to claim 1 which are laminated in a multilayer structure,

wherein it is so positioned that a first connection pile is electrically connected to a second connection pile under a requirement of an electric connection for the first and second connection piles formed in first and second integrated circuits, respectively, which are contacted to each other in the multilayer structure, and

wherein it is so positioned the first connection pile is not electrically connected to the second connection pile under no requirement of the electric connection for the first and second connection piles.

6. (New) The integrated circuit device according to claim 1, wherein the insulator is not formed on the at least one connection pile.

7. (New) The integrated circuit device according to claim 1, wherein the insulator is formed only on the second surface of the substrate.

8. (New) The integrated circuit device according to claim 1, wherein a plurality of connection piles are exposed through the insulator.

9. (New) The integrated circuit device according to claim 1, wherein a plurality of piles are co-planar with an exposed surface of the insulator.